

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	14	laser near2 (diode (solid adj state)) and resonat\$3 with pulse with (size length duration range) and (modulat\$4 conver\$4 transform\$5 chang\$4 alter\$5 modif\$8) with pulse near3 (size length duration) near4 (shorter smaller reduc\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 10:09
S2	5	S1 and microsec\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 10:18
S3	14	S1 and (\$6sec \$6second \$6seconds)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 10:19
S4	6	(visible uv ultraviolet) adj wavelength near5 microsec\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 10:23
S5	3	laser near2 (diode (solid adj state)) and resonat\$3 with pulse with (size length duration range) and (modulat\$4 conver\$4 transform\$5 chang\$4 alter\$5 modif\$8) with pulse adj3 (shorter smaller reduc\$4) adj3 (size length duration)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 10:27
S6	7	laser with resonat\$3 with modulat\$4 with head	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 10:56

S7	2	laser with resonat\$3 with (pocket\$1 cell) with head and pocket \$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:00
S8	303	shutter\$4 with pocket \$1 adj cell	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:05
S9	55	laser same shutter\$4 near5 pocket\$1 adj cell	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:05
S10	202	laser same (shutter\$4 pocket\$1 cell modulat \$4) near3 pulse near (shorter shorten\$3 length smaller reduc \$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:17
S11	3	S10 and resonat\$4 with microsec\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:18
S12	595	laser same (shutter\$4 pocket\$1 modulat\$4) near3 pulse same pulse near2 (shorter shorten \$3 length smaller reduc \$3) not S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:19
S13	5	S12 and resonat\$4 with microsec\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:19
S14	5	S13 and solid with laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:27
S15	4	S13 and solid with state with laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:27

S16	4	S13 and solid with state with laser and diode near4 laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:28
S17	134	"372"/\$.ccls. and pockels.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:30
S18	13	S17 and laser with (machining drilling)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:30
S19	116	laser with solid adj state with resonator with active adj medium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:47
S20	37	S19 and laser same (shutter\$4 pockel\$1 modulat\$4) with pulse same pulse near2 (shorter shorten\$3 length smaller reduc\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 11:47
S21	12	S20 and laser with (machining drill\$4 cut \$4 etch\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 12:31
S22	12	S20 and laser with (machining drill\$4 cut \$4 etch\$4) and laser with diode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 12:31
S23	1	S19 and laser same (shutter\$4 pockel\$1 modulat\$4) with pulse same pulse near2 (shorter shorten\$3 smaller reduc\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 12:35
S24	49	S19 and pulse near2 (shorter shorten\$3 smaller reduc\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 12:35

S25	17	S24 and laser with (machining drill\$4 cut \$4 etch\$4) and laser with diode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 12:36
S26	17	S25 and (microsec\$4 sec\$4 ms msec)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 12:45
S27	17	S25 and (microsec\$4 ms msec)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 12:45
S28	16	S25 and (microsec\$4 msec)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 12:45
S29	157	modulat\$4 with microsec\$4 with millisecc\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:05
S30	6	modulat\$4 with microsec\$4 with millisecc\$4 same pulse near2 (shorter shorten\$3 smaller reduc\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:06
S31	0	(modulat\$4 pockel\$1) with microsec\$4 with millisecc\$4 same pulse near2 (shorter shorten\$3 smaller reduc\$3) not S30	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:09
S32	0	(modulat\$4 pockel\$1 shutter) with microsec\$4 with millisecc\$4 same pulse near2 (shorter shorten\$3 smaller reduc\$3) not S30	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:09
S33	2295	(modulat\$4 pockel\$1 shutter) with pulse near2 (shorter shorten\$3 smaller reduc\$3) same pulse near2 (shorter shorten\$3 smaller reduc\$3) not S30	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:10

S34	65	laser with (machining drill\$4 cut\$4 etch\$4) and laser with diode and laser same (modulat\$4 pockel\$1 shutter) with pulse near2 (shorter shorten \$3 smaller reduc\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:12
S35	7	laser with (machining drill\$4 cut\$4 etch\$4) and laser with diode and laser same (modulat\$4 pockel\$1 shutter) with pulse near2 (shorter shorten \$3 smaller reduc\$3) same train	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:19
S36	5	laser with (machining drill\$4 cut\$4 etch\$4) and laser with diode and laser same (modulat\$4 pockel\$1 shutter) with pulse near2 (shorter shorten \$3 smaller reduc\$3) and train with pulse near2 (shorter shorten \$3 smaller reduc\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:19
S37	5	laser same (machining drill\$4 cut\$4 etch\$4) and laser with diode and laser same (modulat\$4 pockel\$1 shutter) same pulse near2 (shorter shorten \$3 smaller reduc\$3) and train with pulse near2 (shorter shorten \$3 smaller reduc\$3) not S36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:20
S38	0	laser same (machining drill\$4 cut\$4 etch\$4) and laser near3 (solid diode) with resonat\$4 and laser same (modulat\$4 pockel\$1 shutter) same pulse near2 (shorter shorten \$3 smaller reduc\$3) and train with pulse near2 (shorter shorten \$3 smaller reduc\$3) not S36 not S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:26

S39	0	laser same (machining drill\$4 cut\$4 etch\$4) and laser with (solid diode) with resonat\$4 and (laser beam pulse wavelength) with (modulat\$4 pockel\$1 shutter) same (pulse wavelength) near2 (shorter shorten\$3 smaller reduc\$3) and train with (pulse wavelength) near2 (shorter shorten\$3 smaller reduc\$3) not S36 not S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:28
S40	0	laser same (machining drill\$4 cut\$4 etch\$4) and (solid diode) with resonat\$4 and (laser beam pulse wavelength) with (modulat\$4 pockel\$1 shutter) same (pulse wavelength) near2 (shorter shorten\$3 smaller reduc\$3) and train with (pulse wavelength) near2 (shorter shorten\$3 smaller reduc\$3) not S36 not S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:28
S41	2	laser same (machining drill\$4 cut\$4 etch\$4) and (solid diode) with resonat\$4 and (modulat\$4 pockel\$1 shutter) same (pulse wavelength) near2 (shorter shorten\$3 smaller reduc\$3) and train with (pulse wavelength) near3 (shorter shorten\$3 smaller reduc\$3) not S36 not S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:29

S42	2	laser same (machining drill\$4 cut\$4 etch\$4) and (solid diode) with resonat\$4 and (modulat\$4 pockel\$1 shutter) same (pulse wavelength) near2 (shorter shorten\$3 smaller reduc\$3) and train with (pulse wavelength) near3 (shorter shorten\$3 smaller reduc\$3) not S36 not S37 and modulat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:36
S43	54	laser same (machining drill\$4 cut\$4 etch\$4) with lithography and (solid diode) with resonat\$4 and (modulat\$4 pockel\$1 shutter)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:42
S44	7	laser same (machining drill\$4 cut\$4 etch\$4) with lithography and (solid diode) with resonat\$4 with (modulat\$4 pockel\$1 shutter)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:42
S45	0	laser same (machining drill\$4 cut\$4 etch\$4 lithography) and (solid diode) with laser and laser with resonat\$4 with (modulat\$4 pockel\$1 shutter) and single adj pulse with (conver\$4 chang\$4) with train	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:57
S46	0	laser same (machining drill\$4 cut\$4 etch\$4 lithography) and (solid diode) with laser and laser with resonat\$4 with (modulat\$4 pockel\$1 shutter) and single adj pulse with (conver\$4 chang\$4) with (train sequence)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:57

S47	0	laser same (machining drill\$4 cut\$4 etch\$4 lithography) and (solid diode) with (laser medium) and resonat \$4 with (modulat\$4 pockel\$1 shutter) and single adj pulse with (conver\$4 chang\$4) with (train sequence)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:58
S48	0	laser same (machining drill\$4 cut\$4 etch\$4 lithography) and (solid diode) with (laser medium) and resonat \$4 same (modulat\$4 pockel\$1 shutter) and single adj pulse with (conver\$4 chang\$4) with (train sequence)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 13:59
S49	60	laser same (machining drill\$4 cut\$4 etch\$4 lithography) and (solid diode) with (laser medium) and laser with (modulat\$4 pockel \$1 shutter) and single adj pulse with (train sequence)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 14:00
S50	12	laser same (machining drill\$4 cut\$4 etch\$4 lithography) and (solid diode) with (laser medium) and laser with (modulat\$4 pockel \$1 shutter) and single adj pulse with output \$4 with (train sequence)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 14:00
S51	105	372/9-32.cds. and pockel\$1.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 14:11
S52	30	372/9-32.cds. and pockel\$1.clm. and ((laser resonat\$4) near5 (solid diode)). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 14:11



S53	26	372/9-32.ccls. and (pocket\$1 modulat\$4). clm. and ((laser resonat\$4) near5 (solid diode)).clm. and pulse with microsec\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 14:27
S54	16	S53 and laser same (machining drill\$4 cut \$4 etch\$4 lithography)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 14:29
S55	5	modulation with between with resonat \$4 with head	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 14:44
S56	0	pulse near2 modulat\$4 with resonat\$4 with head same laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 14:45
S57	2	pulse near2 modulat\$4 with resonat\$4 with focus\$4 same laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 14:46
S58	26	pulse near2 modulat\$4 same resonat\$4 same (head focus\$4 lens) same laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 14:47
S59	7	pulse near2 modulat\$4 same resonat\$4 same (head focus\$4 lens) same laser and laser with (machining cut\$4 drill\$4 punch\$4 etch\$4 ablat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 14:47
S60	5	"2002000426"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 14:56
S61	2	"2002000426"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 14:56

S62	0	modulat\$4 near4 outside adj3 cavity same (divid\$4 subdivid \$4 division) near7 train same laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:00
S63	0	modulat\$4 near4 outside adj3 cavity same (divid\$4 subdivid \$4 division) near7 train	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:00
S64	0	modulat\$4 near4 outside adj3 cavity same (divid\$4 subdivid \$4 division)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:00
S65	0	modulat\$4 near4 outside adj3 (cavity resona\$7) same (divid \$4 subdivid\$4 division)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:01
S66	92	modulat\$4 near4 outside adj3 (cavity resona\$7)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:01
S67	76	laser same modulat\$4 near4 outside adj3 (cavity resona\$7)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:01
S68	37	S67 and laser same (machining drill\$4 cut \$4 etch\$4 lithography)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:01
S69	35	laser same modulat\$4 near4 outside adj3 (cavity resona\$7) and pulse near5 (length size duration short\$5 reduc\$5 chang\$4 alter \$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:06
S70	35	laser same modulat\$4 near4 outside adj3 (cavity resona\$7) and pulse near2 (length size duration short\$5 reduc\$5 chang\$4 alter \$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:06

S71	3	laser same modulat\$4 near4 outside adj3 (cavity resona\$7) and (secondary output\$5 emit\$4 exit\$4 leav\$4) adj4 pulse near2 (length size duration short\$5 reduc\$5 chang \$4 alter\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:07
S72	3	laser same (modulat\$4 pockel\$1 shutter\$3) near4 outside adj3 (cavity resona\$7) and (secondary output\$5 emit\$4 exit\$4 leav\$4) adj4 pulse near2 (length size duration short\$5 reduc\$5 chang \$4 alter\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:16
S73	25	laser same (modulat\$4 pockel\$1 shutter\$3) near4 (outside external \$4 adjacent sep?rat\$4) adj3 (cavity resona\$7) and (secondary output \$5 emit\$4 exit\$4 leav \$4) near4 pulse near2 (length size duration short\$5 reduc\$5 chang \$4 alter\$5) not S72	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:18
S74	16	S73 and laser same (machining drill\$4 cut \$4 etch\$4 lithography)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:19
S75	14	S74 and laser with diode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:20
S76	14	S74 and laser near5 (diode (solid adj state))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:20
S77	0	S74 and laser near5 (diode (solid adj state)) and microsecond same millisecond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:22

S78	7	S74 and laser near5 (diode (solid adj state)) and microsecond same millisecond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:22
S79	9	S74 not S78	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:25
S80	9	S73 not S78 not S79	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:28
S81	56	("20020000426"   "20020009843"   "20030069617"   "20050254533"   "20060256693"   "4114018"   "4227159"   "4399529"   "4581515"   "5121398"   "5173918"   "5377212"   "5381437"   "5828683"   "5943351"   "5963575"   "6130900"   "6366596"   "6414980"   "6418154"   "6449294"   "6539035"   "6541731"   "6664498"   "6683893"   "7113533"   "7149231").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:32
S82	14	S81 and modulat\$4 with pulse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/10 15:34
S83	232	372/9-32.cds. and (pockel\$1 modulat\$4) near5 (resonat\$4 laser) with pulse and ((laser resonat\$4) near5 (solid diode)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 12:28

S84	72	372/9-32.ccls. and (pockel\$1 modulat\$4) near5 (resonat\$4 laser) with pulse same pulse near2 train and ((laser resonat\$4) near5 (solid diode))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 12:28
S85	1	372/9-32.ccls. and (pockel\$1 modulat\$4) near5 (resonat\$4 and laser) with pulse same pulse near2 train and ((laser resonat\$4) near5 (solid diode))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 12:29
S86	7	372/9-32.ccls. and laser same (pockel\$1 modulat\$4) with resonat\$4 with pulse same pulse near2 train and ((laser resonat\$4) near5 (solid diode))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 12:37
S87	4	372/9-32.ccls. and laser same (pockel\$1 modulat\$4) near3 external\$4 with resonat\$4 with pulse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 12:39
S88	0	372/9-32.ccls. and laser with pulse same (pockel\$1 modulat\$4) near3 outside adj3 resonat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 12:44
S89	3	372/9-32.ccls. and (pockel\$1 modulat\$4) near3 outside adj3 resonat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 12:44
S90	12	372/9-32.ccls. and (pockel\$1 modulat\$4) near3 out\$8 adj3 resonat\$4 not S89	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 12:49
S91	2	S90 and pockel\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 12:54
S92	0	pockel\$1 near3 out\$8 adj3 resonat\$4 not S89 not S90	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 12:56

S93	10	pockel\$1 near3 out\$8 with resonat\$4 not S89 not S90	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 12:57
S94	13	pockel\$1 near3 head	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 12:59
S95	0	S94 and pulse with microsec\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:04
S96	2	S94 and pulse with (\$1sec \$1second micro \$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:05
S97	2	S94 and pulse with pockel\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:08
S98	2	S94 and pump\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:14
S99	6894	diode near5 laser and optical\$4 near2 pump \$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:15
S100	2267	diode near5 laser same optical\$4 near2 pump \$3 with diode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:15
S101	587	laser with (machining drill\$4 cut\$4 etch\$4) and diode near5 laser same optical\$4 near2 pump\$3 with diode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:16
S102	62	laser with (machining drill\$4 cut\$4 etch\$4) and diode near5 laser same optical\$4 near2 pump\$3 with diode and pockel\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:16

S103	9	laser with (machining drill\$4 cut\$4 etch\$4) and diode near5 laser same optical\$4 near2 pump\$3 with diode and pockel\$1 with resonat \$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:17
S104	8	laser with (machining drill\$4 cut\$4 etch\$4) and diode near5 laser same optical\$4 near2 pump\$3 with diode and modulat\$5 with out\$5 with resonat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:20
S105	6	laser with (machining drill\$4 cut\$4 etch\$4) and diode near5 laser same optical\$4 near2 pump\$3 with diode and modulat\$5 near5 head	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:22
S106	3	laser with (machining drill\$4 cut\$4 etch\$4) and diode near5 laser same optical\$4 near2 pump\$3 with diode and (modulat\$5 shutter\$3 cell pockel\$1) near5 head not S105	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:23
S107	7	laser with (machining drill\$4 cut\$4 etch\$4) and diode near5 laser same optical\$4 near2 pump\$3 with diode same head	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:24
S108	4	S107 and pump\$4 with mirror	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:26
S109	7	S107 and pump\$4 near2 laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:31
S110	18	pump\$4 near2 laser with reflect\$4 with mirrors same head	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:32
S111	2	((("6782016") or ("7316067"))).PN.	USPAT; USOCR	OR	OFF	2009/09/11 13:48

S112	2	S111 and ((solid state diode) with laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:49
S113	1	S111 and pulse with (width length)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:55
S114	0	S111 and (more less) adj2 pulse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:56
S115	0	S111 and short\$5 adj2 pulse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:56
S116	0	S111 and reduc\$5 near2 pulse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:56
S117	2	S111 and pulse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:57
S118	1	S111 and pulse near2 energy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 13:57
S119	37	modulat\$4 near3 pulse with short\$5 adj length	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 14:00
S120	12	modulat\$4 near3 pulse with short\$5 adj length same laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 14:02
S121	88	modulat\$4 near3 pulse with short\$5 near2 (length width wavelength) same laser not S120	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 14:03



S122	28	modulat\$4 near3 pulse with short\$5 near (length width wavelength) same laser not S120	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 14:04
S123	0	S122 and "219"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 14:05
S124	0	S122 and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 14:05
S125	0	S122 and "29"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 14:06
S126	1422	laser with pulse with short\$5 near (length width wavelength) not S120	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 14:06
S127	143	laser with pulse near3 shorten\$3 near (length width wavelength) not S120	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 14:07
S128	10	S127 and "219"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/11 14:07

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